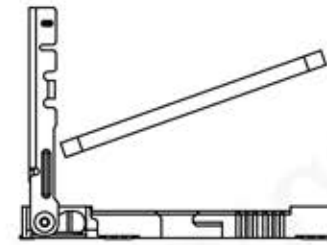
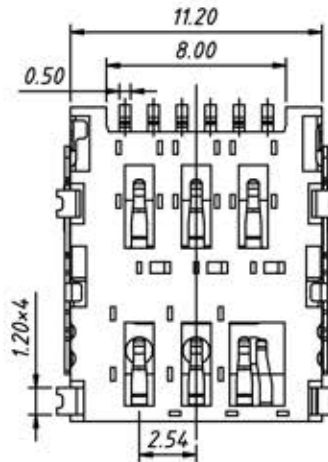
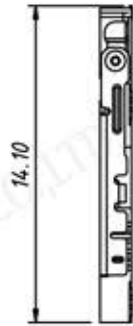
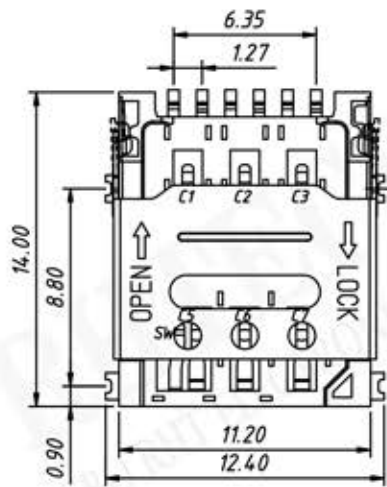
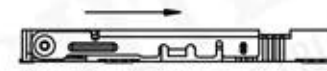


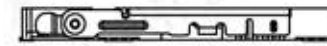
P/N: RE-C-SIM-077A-6P-H1.4-R



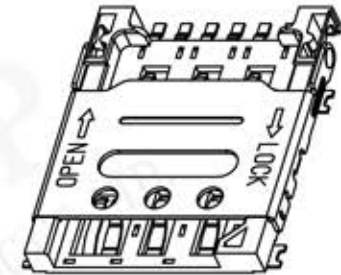
STEP 1 INSERT NANO SIM CARD



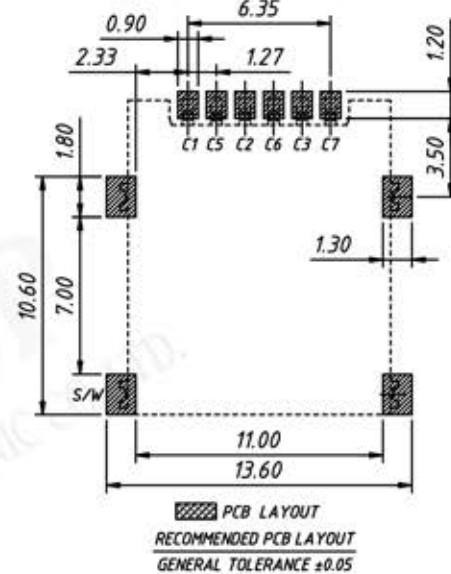
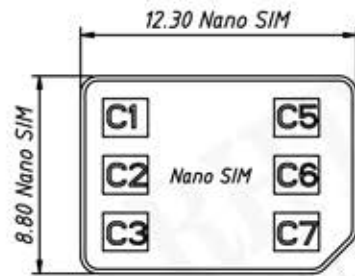
STEP 2 PUSH THE SHELL



STEP 3 FINISH



**Material:**  
 Insulator: High Temperature Thermoplastic, UL 94V-0.  
 Contact: Copper Alloy, Plated 50u"  
 Ni Overall Contact All Au 1U.  
 Shell: SUS. All Ni 30U/MIN.



Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
S/W	SWITSH PIN

**Electrical:**  
 Current Rating: 0.5A AC/DC MAX.  
 Voltage Rating: 125V AC/DC  
 Ambient Temperature Range: -20°C ~ +60°C  
 Storage Temperature Range: -40°C ~ +70°C  
 Ambient Humidity Range: 95% R.H. Max.  
 Contact Resistance: 80mΩ Max.  
 Insulation Resistance: 100MΩ Min./100V DC  
 Mating Cycles: 5000 Insertions.  
 Reflow peak temp: 260°C ±5°C, 3~5 s

